IPC ASSOCIATION CO ELECTRONICS IN	Material Components (Construes) (Copyright 2005. international and Page 1997)	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and M	ials and Mfg Information			
upplier Iı	nformation														
Company nai	me*	Company unique ID			J	Unique ID Authority				Response Date*					
nsemi										2023-00	2023-06-08				
Contact Nam	ne	Title - Contact			I	Phone - Contact*				Email -	Email - Contact*				
Product-Env	y-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized R	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env	y-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
R	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Vers	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		LC05111C23MTTTG 1 cell LiB		1 cell LiB Protection	ell LiB Protection IC		2023-06-08			PHM		26.64	mg	Each	
Ianufactu	uring Proccess Informa	ation													
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Tempera		ly Temperatu	ture Max Time at Peak Tempera		ture Numb	per of Reflow Cyc	eles		
contains Bi		CU Alloy 3				260 C		C	30	seco	nds 3				
omments															
ITENTION	N: MSL 3 Rated item requir	es Bake and D	ry Pack (after	electrical test)											
or more info	ormation regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.41	mg	Supplier	Silicon (Si)	7440-21-3		2.41	mg
Die Attach Solder	0.89	mg	Supplier	Silver (Ag)	7440-22-4		0.0223	mg
			A	Lead (Pb)	7439-92-1	7a	0.8232	mg
			Supplier	Tin (Sn)	7440-31-5		0.0445	mg
Lead Frame	12.04	mg	Supplier	Silver (Ag)	7440-22-4		0.3612	mg
			Supplier	Tin (Sn)	7440-31-5		0.0181	mg
			Supplier	Copper (Cu)	7440-50-8		11.6607	mg
Mold Compound-Black	10.73	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.073	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0536	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.5558	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.9745	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.073	mg
Plating	0.54	mg	В	Bismuth (Bi)	7440-69-9		0.0041	mg
			Supplier	Tin (Sn)	7440-31-5		0.536	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg